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SINGLE DIGIT LED DISPLAY (0.8 Inch)



Lead-Free Parts

**LSD815/6DBK-XX-PF**

**DATA SHEET**

DOC. NO : QW0905-LSD815/6DBK-XX-PF

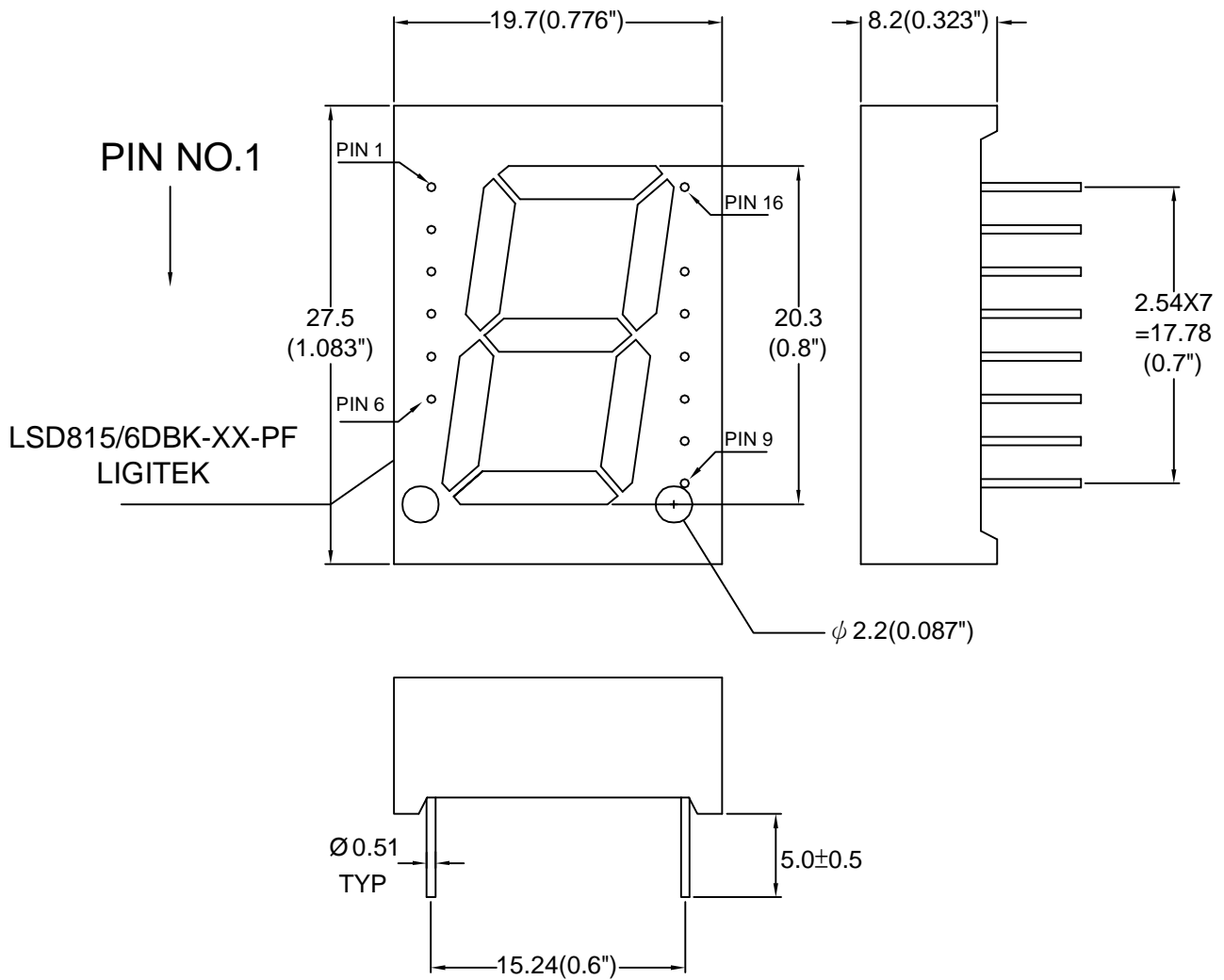
REV. : A

DATE : 07 - Dec. - 2009





### Package Dimensions



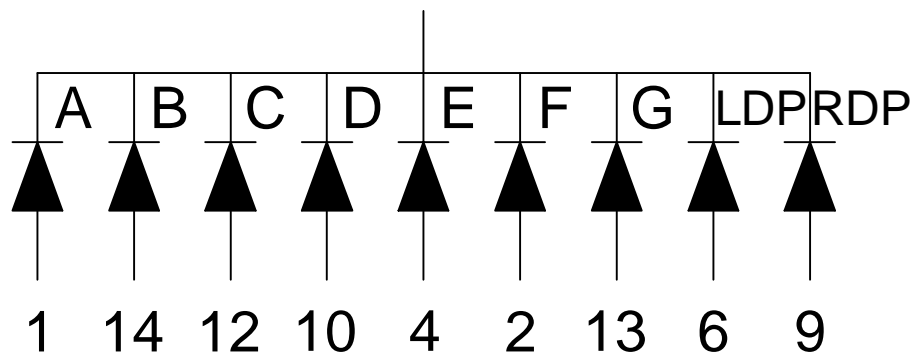
Note : 1.All dimension are in millimeters and (Inch) tolerance is  $\pm 0.25$ mm unless otherwise noted.  
2.Specifications are subject to change without notice.



Internal Circuit Diagram

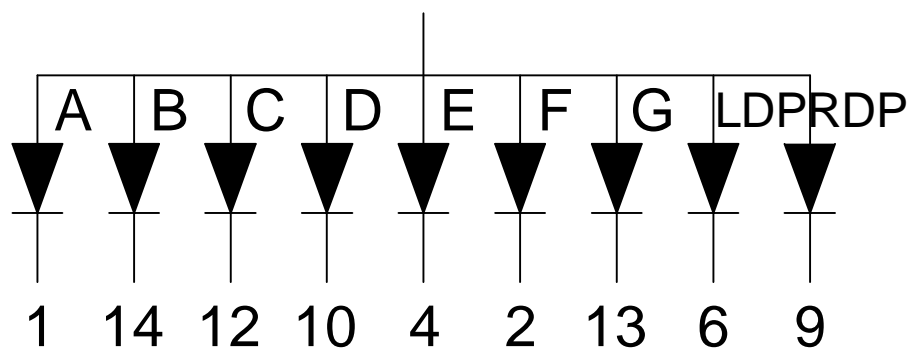
LSD815DBK-XX-PF

3,5,11,16



LSD816DBK-XX-PF

3,5,11,16





### Electrical Connection

PIN NO.	LSD815DBK-XX-PF	PIN NO.	LSD816DBK-XX-PF
1	Anode A	1	Cathode A
2	Anode F	2	Cathode F
3	Common Cathode	3	Common Anode
4	Anode E	4	Cathode E
5	Common Cathode	5	Common Anode
6	Anode LDP	6	Cathode LDP
7	No Pin	7	No Pin
8	No Pin	8	No Pin
9	Anode RDP	9	Cathode RDP
10	Anode D	10	Cathode D
11	Common Cathode	11	Common Anode
12	Anode C	12	Cathode C
13	Anode G	13	Cathode G
14	Anode B	14	Cathode B
15	No Pin	15	No Pin
16	Common Cathode	16	Common Anode



Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Ratings	UNIT
		DBK	
Forward Current Per Chip	IF	30	mA
Peak Forward Current Per Chip (Duty 1/10,0.1ms Pulse Width)	IFP	100	mA
Power Dissipation Per Chip	PD	120	mW
Reverse Current Per Any Chip	Ir	50	μA
Electrostatic Discharge( * )	ESD	500	V
Operating Temperature	Topr	-25 ~ +85	°C
Storage Temperature	Tstg	-25 ~ +85	°C

\* Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling these LED. All devices, equipment and machinery must be properly grounded.

Part Selection And Application Information(Ratings at 25°C)

PART NO	CHIP		common cathode or anode	λ D (nm)	Δ λ (nm)	Electrical				IV-M
	Material	Emitted				Vf(v)		Iv(mcd)		
						Typ.	Max	Min.	Typ.	
LSD815DBK-XX-PF	InGaN/GaN	Blue	Common Cathode	470	30	3.5	4.0	18.0	26.0	2:1
LSD816DBK-XX-PF			Common Anode							

Note : 1. The forward voltage data did not including ±0.1V testing tolerance.  
2. The luminous intensity data did not including ±15% testing tolerance.

**Test Condition For Each Parameter**

Parameter	Symbol	Unit	Test Condition
Forward Voltage Per Chip	$V_f$	volt	$I_f=20\text{mA}$
Luminous Intensity Per Chip	$I_v$	mcd	$I_f=10\text{mA}$
Dominant Wavelength	$\lambda_D$	nm	$I_f=20\text{mA}$
Spectral Line Half-Width	$\Delta \lambda$	nm	$I_f=20\text{mA}$
Reverse Current Any Chip	$I_r$	$\mu A$	$V_r=5V$
Luminous Intensity Matching Ratio	IV-M		



### Typical Electro-Optical Characteristics Curve

DBK CHIP

Fig.1 Forward current vs. Forward Voltage

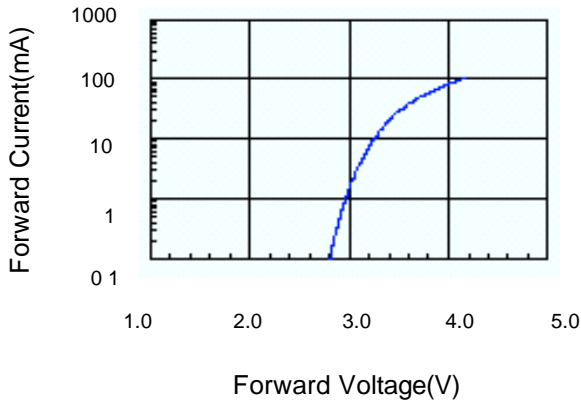


Fig.2 Relative Intensity vs. Forward Current

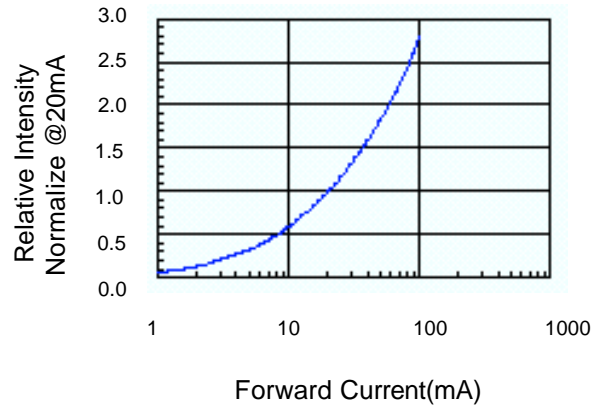


Fig.3 Forward Voltage vs. Temperature

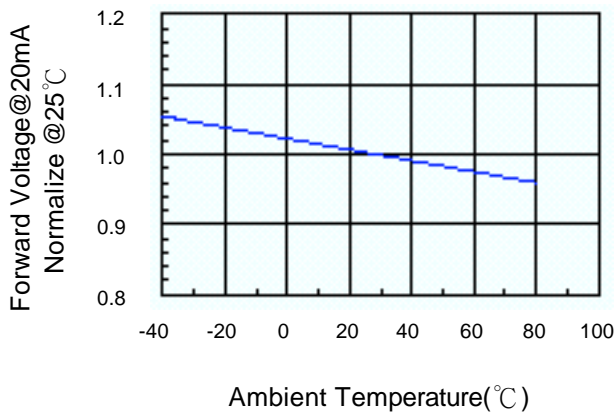


Fig.4 Relative Intensity vs. Temperature

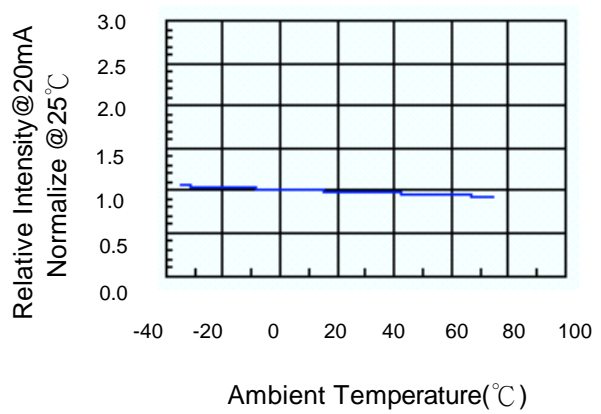
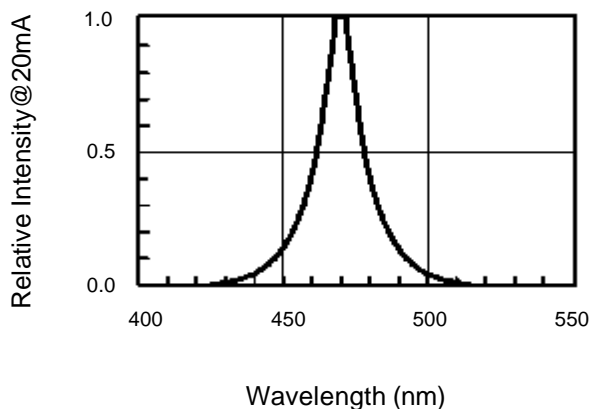


Fig.5 Relative Intensity vs. Wavelength





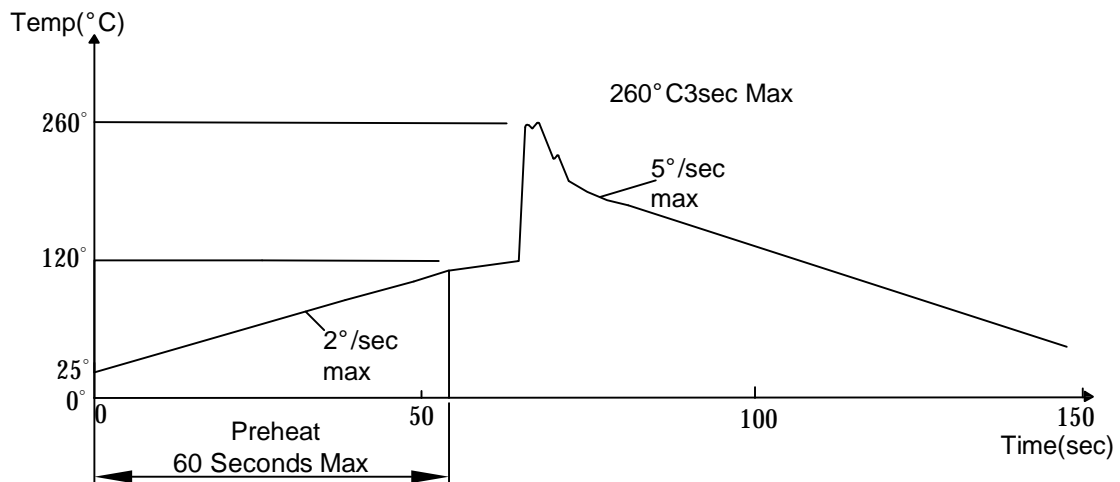
### Soldering Condition(Pb-Free)

#### 1.Iron:

Soldering Iron:30W Max  
Temperature 350° C Max  
Soldering Time:3 Seconds Max(One Time)  
Distance:Solder Temperature 1/16 Inch Below Seating  
Plane For 3 Seconds At 260° C

#### 2.Wave Soldering Profile

Dip Soldering  
Preheat: 120° C Max  
Preheat time: 60seconds Max  
Ramp-up  
2° C/sec(max)  
Ramp-Down:-5° C/sec(max)  
Solder Bath:260° C Max  
Dipping Time:3 seconds Max  
Distance:Solder Temperature 1/16 Inch Below Seating  
Plane For 3 Seconds At 260° C







Reliability Test:

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=10mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 °C±5°C 2.RH=90%~95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 °C±5°C & -40 °C±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 °C±5°C 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 °C±5°C 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2